

Cree® XLamp® XB-G High-Voltage White LEDs



PRODUCT DESCRIPTION

Built on Cree’s SC³ Technology® Platform, the XLamp® XB-G High-Voltage White (HVW) LED is optimized to lower cost for high-lumen, omnidirectional replacement lamps. The XB-G HVW LED delivers high efficacy in the small XB footprint and enables smaller and more efficient driver circuits than standard-voltage LEDs. In addition, the XB-G LED has a wider light distribution that can improve the omnidirectionality of ENERGY STAR® replacement lamps.

FEATURES

- Binned @ 85 °C & 44 mA
- Available in 80-minimum CRI
- 200 mA maximum drive current
- 22.5 V typical forward voltage @ 85 °C, 44 mA
- Wide viewing angle: 140°
- Reflow solderable - JEDEC J-STD-020C compatible
- Unlimited floor life at ≤ 30 °C/85% RH
- Electrically neutral thermal path
- RoHS-compliant
- UL® recognized component (E349212)

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CHARACTERISTICS

| Characteristics | Unit | Minimum | Typical | Maximum |
|--|---------|---------|---------|---------|
| Thermal resistance, junction to solder point | °C/W | | 5.5 | |
| Viewing angle (FWHM) | degrees | | 140 | |
| Temperature coefficient of voltage | mV/°C | | -16 | |
| ESD classification (HBM per Mil-Std-883D) | | | Class 2 | |
| DC forward current | mA | | | 200 |
| Reverse voltage | V | | | -0.1 |
| Forward voltage (@ 44 mA, 85 °C) | V | | 22.5 | 25 |
| LED junction temperature | °C | | | 150 |

FLUX CHARACTERISTICS (T_j = 85 °C)

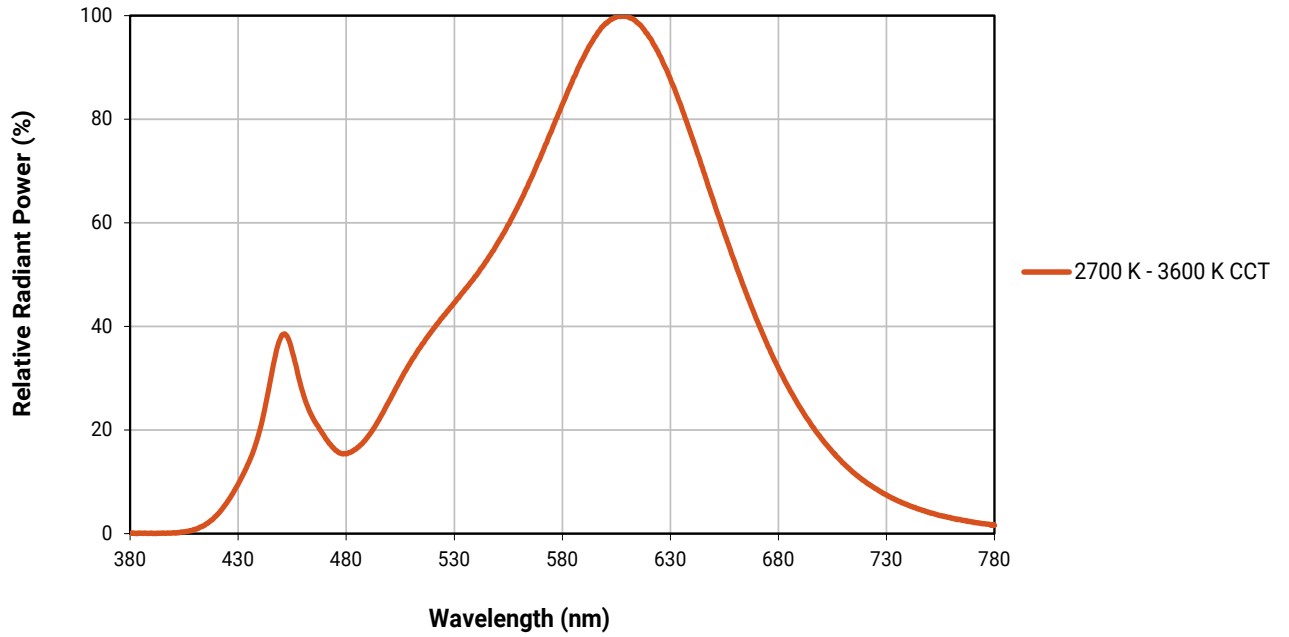
The following table provides several base order codes for XLamp XB-G HVW LEDs. It is important to note that the base order codes listed here are a subset of the total available order codes for the product family. For more order codes, as well as a complete description of the order-code nomenclature, please consult the XLamp XB LED Family Binning and Labeling document.

| Color | CCT Range | | Minimum Luminous Flux @ 44 mA | | | Calculated Minimum Luminous Flux (lm)** | | Order Code |
|----------------|-----------|---------|-------------------------------|-------------------|--------------------|---|--------|--------------------------|
| | Minimum | Maximum | Group | Flux (lm) @ 85 °C | Flux (lm) @ 25 °C* | 66 mA | 100 mA | |
| 80 CRI Minimum | 2700 K | 3000 K | Q5 | 107 | 120 | 153 | 216 | XBGHVW-H0-0000-00000HDE7 |
| | | | Q4 | 100 | 112 | 143 | 202 | XBGHVW-H0-0000-00000HCF8 |
| | | | Q3 | 93.9 | 105 | 134 | 190 | XBGHVW-H0-0000-00000HBE8 |

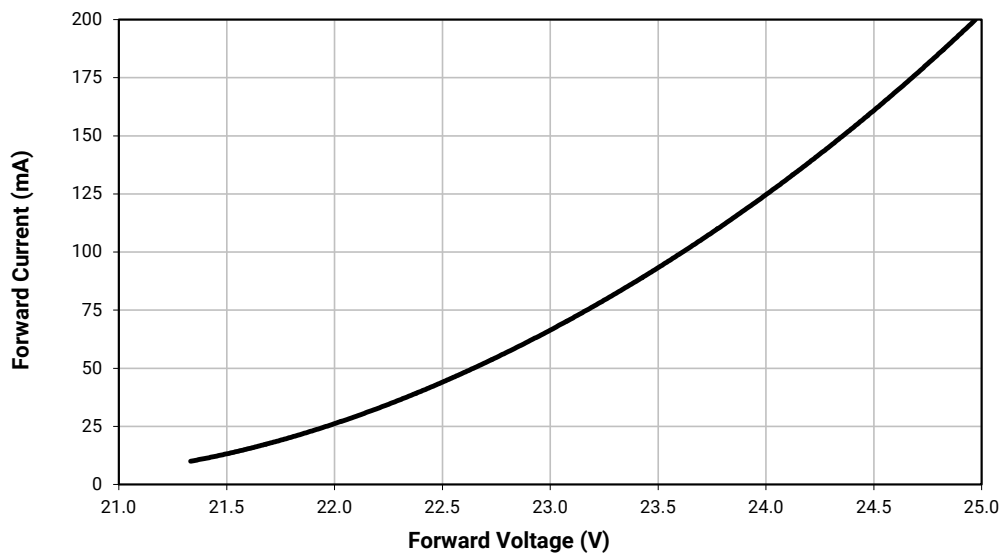
Notes:

- Cree maintains a tolerance of ±7% on flux and power measurements, ±0.005 on chromaticity (CCx, CCy) measurements and ±2 on CRI measurements. See the Measurements section (page 7).
- Minimum CRI for 80 CRI Minimum is 80.
- * Flux values @ 25 °C are calculated and are for reference only.
- ** Calculated flux values at 66 mA and 100 mA are for 85 °C and are for reference only.

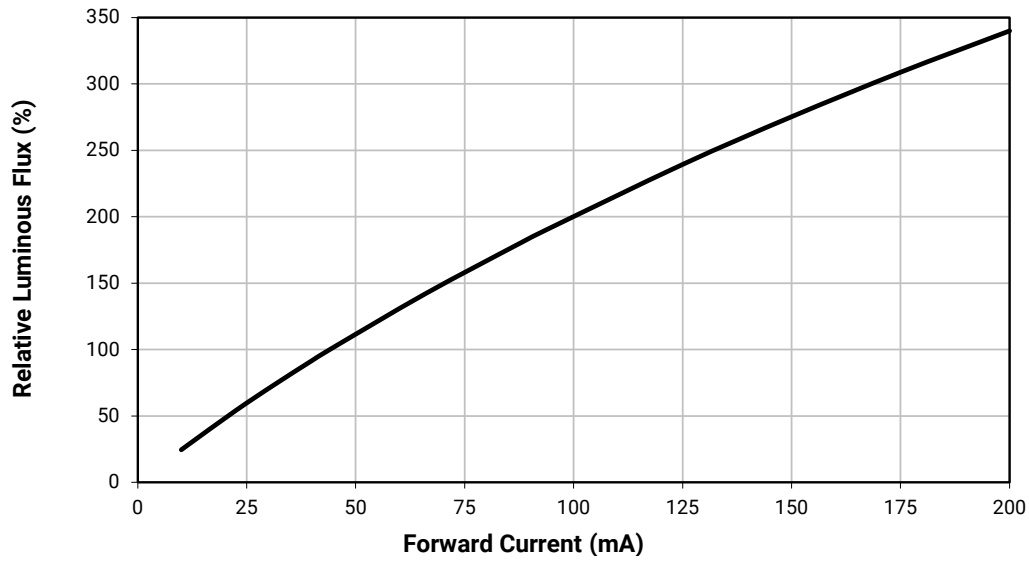
RELATIVE SPECTRAL POWER DISTRIBUTION



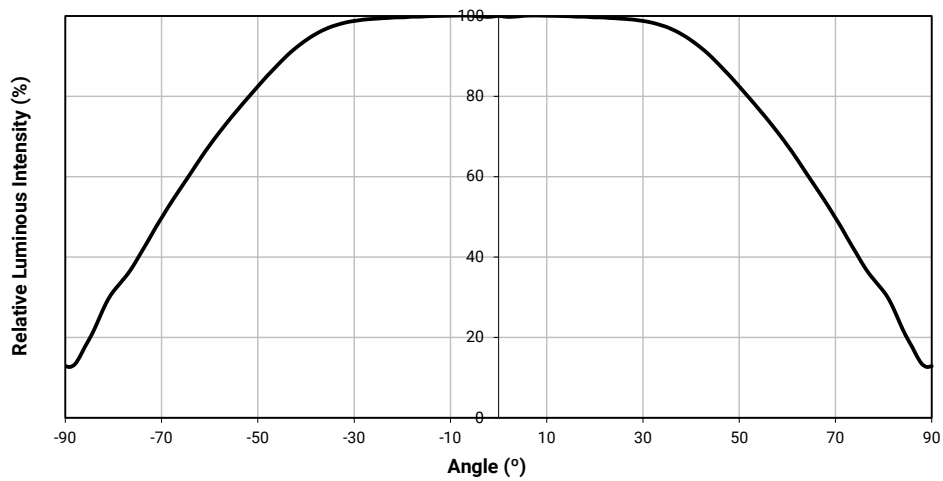
ELECTRICAL CHARACTERISTICS ($T_j = 85^\circ\text{C}$)



RELATIVE FLUX VS. CURRENT ($T_j = 85\text{ }^\circ\text{C}$)

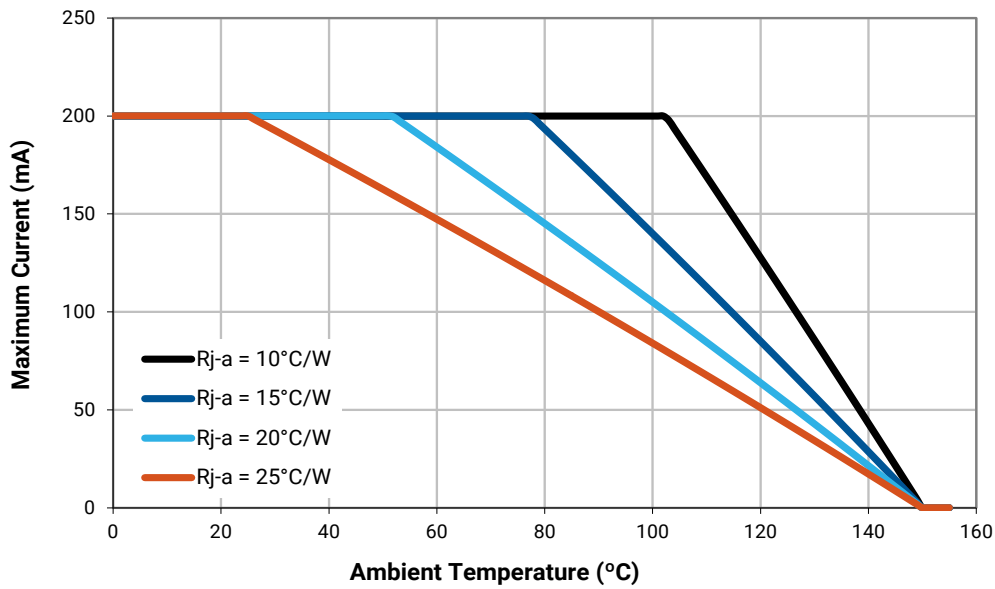


TYPICAL SPATIAL DISTRIBUTION



THERMAL DESIGN

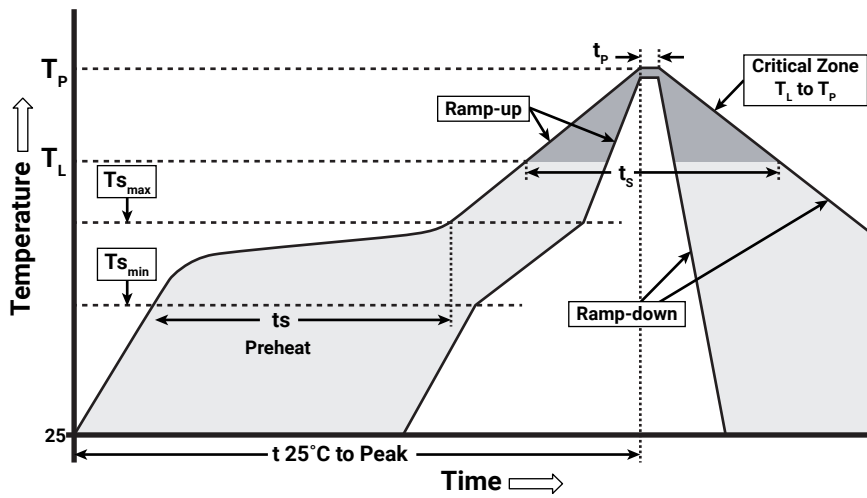
The maximum forward current is determined by the thermal resistance between the LED junction and ambient. It is crucial for the end product to be designed in a manner that minimizes the thermal resistance from the solder point to ambient in order to optimize lamp life and optical characteristics.



REFLOW SOLDERING CHARACTERISTICS

In testing, Cree has found XLamp XB-G HVW LEDs to be compatible with JEDEC J-STD-020C, using the parameters listed below. As a general guideline, Cree recommends that users follow the recommended soldering profile provided by the manufacturer of the solder paste used.

Note that this general guideline may not apply to all PCB designs and configurations of reflow soldering equipment.



IPC/JEDEC J-STD-020C

| Profile Feature | Lead-Free Solder |
|---|------------------|
| Average Ramp-Up Rate ($T_{s_{max}}$ to T_P) | 1.2 °C/second |
| Preheat: Temperature Min ($T_{s_{min}}$) | 120 °C |
| Preheat: Temperature Max ($T_{s_{max}}$) | 170 °C |
| Preheat: Time ($t_{s_{min}}$ to $t_{s_{max}}$) | 65-150 seconds |
| Time Maintained Above: Temperature (T_L) | 217 °C |
| Time Maintained Above: Time (t_l) | 45-90 seconds |
| Peak/Classification Temperature (T_P) | 235 - 245 °C |
| Time Within 5 °C of Actual Peak Temperature (t_p) | 20-40 seconds |
| Ramp-Down Rate | 1 - 6 °C/second |
| Time 25 °C to Peak Temperature | 4 minutes max. |

Note: All temperatures refer to topside of the package, measured on the package body surface.

NOTES

Measurements

The luminous flux, radiant power, chromaticity and CRI measurements in this document are binning specifications only and solely represent product measurements as of the date of shipment. These measurements will change over time based on a number of factors that are not within Cree's control and are not intended or provided as operational specifications for the products. Calculated values are provided for informational purposes only and are not intended as specifications.

Pre-Release Qualification Testing

Please read the [LED Reliability Overview](#) for details of the qualification process Cree applies to ensure long-term reliability for XLamp LEDs and details of Cree's pre-release qualification testing for XLamp LEDs.

Lumen Maintenance

Cree now uses standardized IES LM-80-08 and TM-21-11 methods for collecting long-term data and extrapolating LED lumen maintenance. For information on the specific LM-80 data sets available for this LED, refer to the public [LM-80 results document](#).

Please read the [Long-Term Lumen Maintenance application note](#) for more details on Cree's lumen maintenance testing and forecasting. Please read the [Thermal Management application note](#) for details on how thermal design, ambient temperature, and drive current affect the LED junction temperature.

Moisture Sensitivity

Cree recommends keeping XLamp LEDs in the provided, resealable moisture-barrier packaging (MBP) until immediately prior to soldering. Unopened MBPs that contain XLamp LEDs do not need special storage for moisture sensitivity.

Once the MBP is opened, XLamp XB-G HVW LEDs may be stored as MSL 1 per JEDEC J-STD-033, meaning they have unlimited floor life in conditions of ≤ 30 °C/85% relative humidity (RH). Regardless of storage condition, Cree recommends sealing any unsoldered LEDs in the original MBP.

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of www.cree.com.

UL® Recognized Component

Level 4 enclosure consideration. The LED package or a portion thereof has been investigated as a fire and electrical enclosure per ANSI/UL 8750.

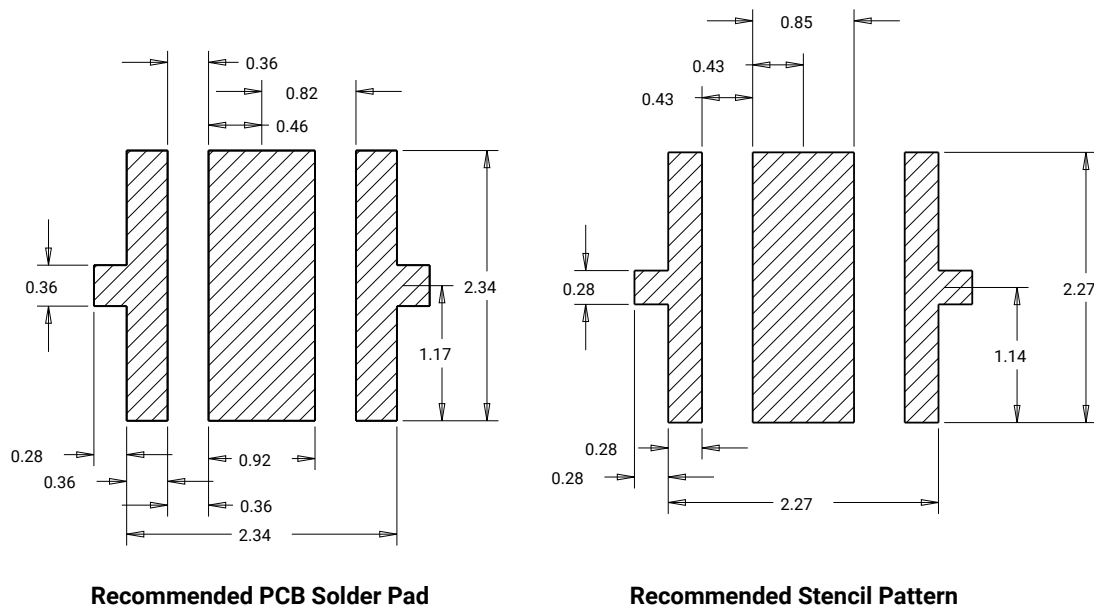
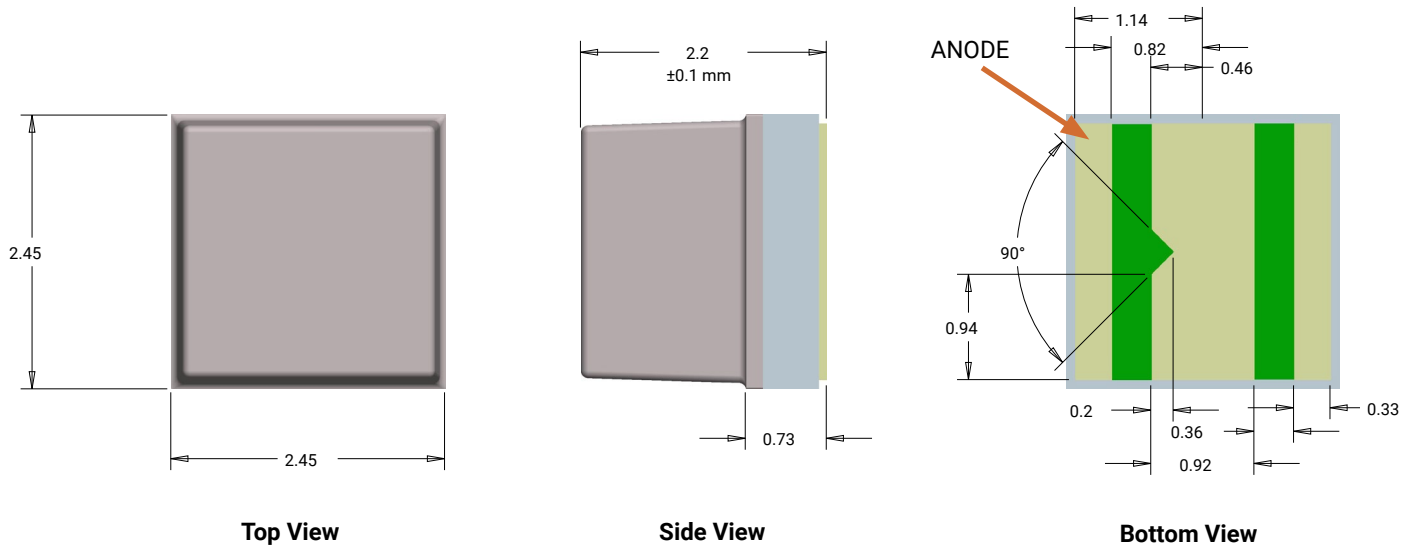
Vision Advisory

WARNING: Do not look at exposed lamp in operation. Eye injury can result. For more information about LEDs and eye safety, please refer to the [LED Eye Safety application note](#).

MECHANICAL DIMENSIONS

Thermal vias, if present, are not shown on these drawings.

All measurements are ± 0.13 mm unless otherwise indicated.

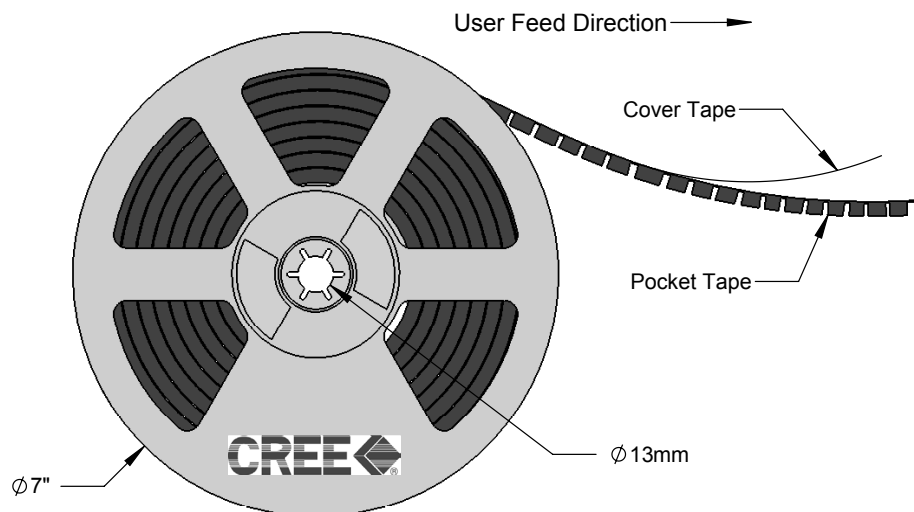
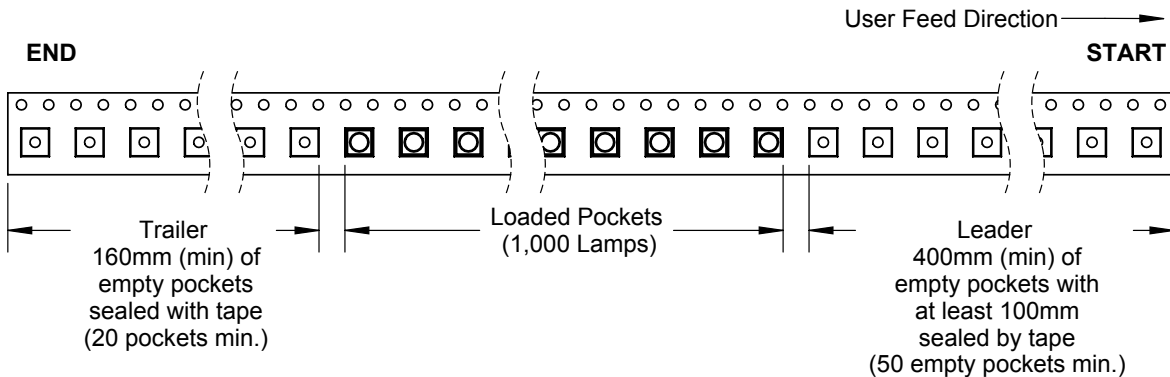
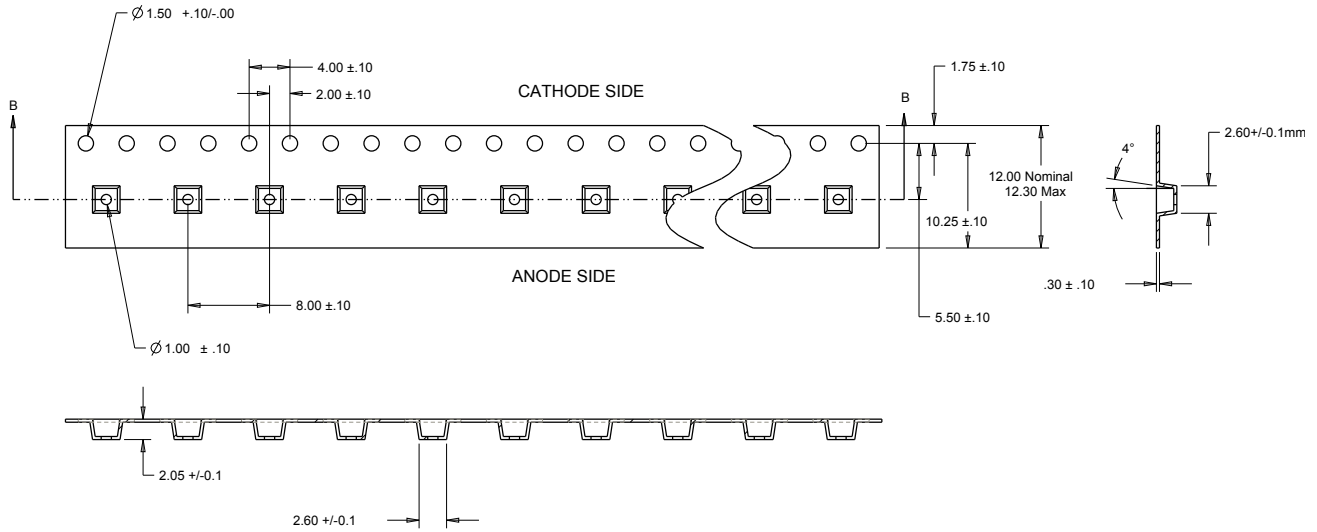


TAPE AND REEL

All Cree carrier tapes conform to EIA-481D, Automated Component Handling Systems Standard.

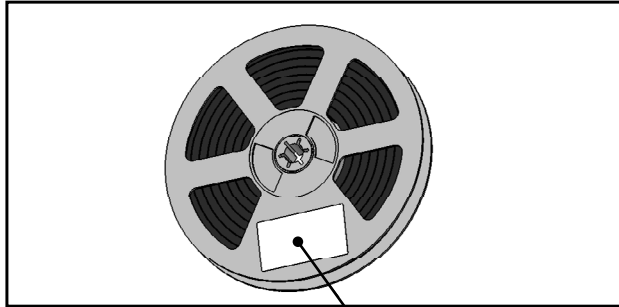
All dimensions in mm

Tolerance unless specified: .xx ± .25, .xxx ± .125, x° ± .5°



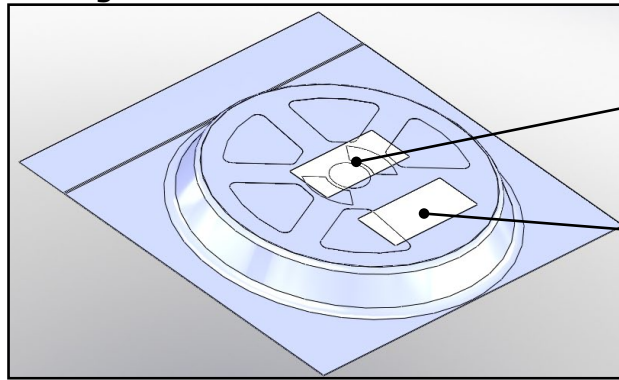
PACKAGING

Unpackaged Reel



Label with Cree Bin Code,
Quantity, Reel ID

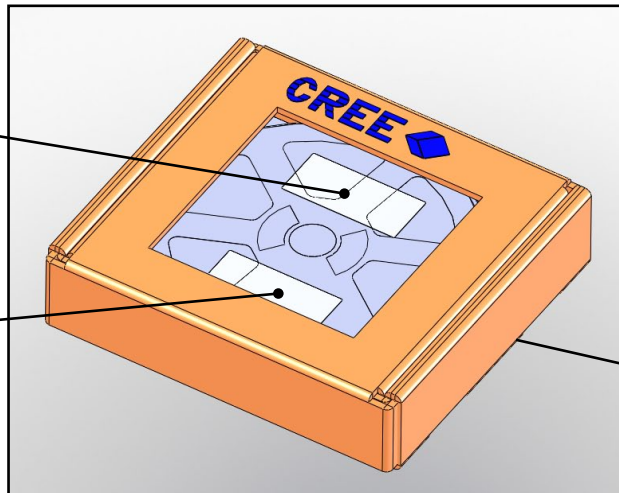
Packaged Reel



Label with Cree Order Code,
Quantity, Reel ID, PO #

Label with Cree Bin Code,
Quantity, Reel ID

Boxed Reel



Label with Cree Order Code,
Quantity, Reel ID, PO #

Label with Cree Bin Code,
Quantity, Reel ID

Patent Label
(on bottom of box)